

means above said die is less than the thickness on the other portions of said molding means ; and

a heat-spreading device which is attached atop said molding compound to conduct heat from said die to ambient air, wherein said head spreading device has a downward bump aligned to said ~~concave~~ recessed portion, and said molding compound exits between said downward bump and said die; and

~~electrically insulated a conductivity or conductive below said substrate to said recessed portion and fully covered by said molding means ; and~~
thickness of said molding means above said die is less than the thickness on the other portions of said molding means; and

heat-spreading means for conducting heat from said die to ambient air by attaching atop said molding means , wherein said head spreading means has a downward bump aligned to said ~~concave~~ recessed portion, and said molding compound exits between said downward bump and said die.

** TOTAL PAGE.03 **

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